

CURING PROCESSES FOR SUBSTRATE IMPRINTING,
STRUCTURES MADE THEREBY,
AND POLYMERS USED THEREFOR

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ABSTRACT OF THE DISCLOSURE

A mounting substrate includes an at least double-embossed structure on one side for containing metallization traces. The mounting substrate is overlaid with an uncured polymer and it is imprinted and cured by infrared or microwave energy. A second uncured polymer is placed over the cured polymer first film. It is imprinted and also cured under conditions that allow retention of significant features of the cured polymer first film. A chip package is also made of the double-embossed structure. The chip package can include a heat sink. A computing system is also disclosed that includes the double-embossed structure.

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